

SV260

Leading in Vapor Phase Technology

Economy Vapor Phase Soldering Machine for Small Series and Prototyping

IBL



The Machine

The SV260 reflow vapor phase soldering machine is perfect for small volume production and offers superior solder quality. It is ideal for development, NPI and prototype production as well as for soldering BGAs and LGAs.

Overview

- Table-top unit with front loading
- 2-chamber design for low consumption
- Oxygen free soldering
- No overheating of components
- No ΔT 's throughout the assembly

Standard Equipment / Specification

- Easy accessible loading and unloading area
- Integrated cooling fan for board cooling
- Fully automatic solder cycle
- Solder automatic
- Energy management system
- Fluid level check
- Observation window to process chamber

Special features

- Maintenance-free transport system (**patented**)
- Low fluid consumption with 2-chamber design and fluid recovery
- Program memory up to 10 programs
- Easy profil recording option

Options

- Adapter for double sided PCB boards
- ReSy, a device for repair of QFP's and BGA's
- Stainless steel grid for the workpiece carrier
- Closed-loop-chiller
- TE-Option for external profile monitoring
- USB profiling system
- Movable under-desk

Technical Data	SV260
Length (over all)	790 mm
Depth	710 mm
Height	640 mm
Weight	90 kg
Max. board size	300 x 260 x 80 mm
Liquid agent filling	3 kg
Water connection	1/2" / 2,5-5 bar / 0,5l/min
Max. heating capacity	2,1 kW
Ø power consumption/h	0,9 kW/h
Power supply	205-240 VAC 2,2 KW
Main fuse	16 A, Typ "gL" or "C"

- Technical changes reserved -

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